MA2ZD18

Silicon epitaxial planar type

For super high speed switching

■ Features

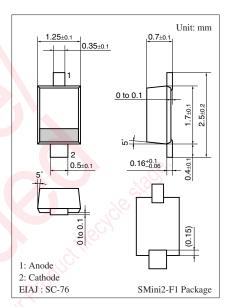
• Low forward voltage V_F

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol Rating		Unit	
Reverse voltage	V_R	20	V	
Repetitive peak reverse voltage	V _{RRM}	25	V	
Forward current (Average) *1	I _{F(AV)}	500	mA	
Non-repetitive peak forward surge current *2	I _{FSM}	2	A	
Junction temperature	T _j	125	°C	
Storage temperature	T _{stg}	-55 to +125	°C	

Note) *1: Mounted on an alumina PC board

*2: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)



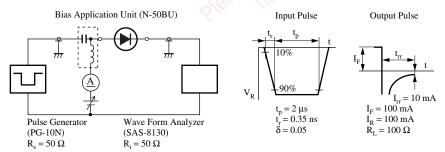
Marking Symbol: 2P

■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

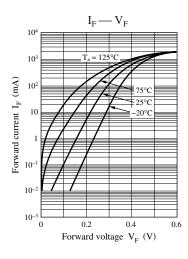
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V _F	$I_F = 500 \text{ mA}$	~0)),	0/1/2	0.42	V
Reverse current	I_R	$V_R = 20 \text{ V}$	2	55	200	μΑ
Terminal capacitance	C_{t}	$V_R = 0 V, f = 1 MHz$	00)	100		pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 100 \text{ mA}$	7.7	7		ns
-6/		$I_{rr} = 10 \text{ mA}, R_{L} = 100 \Omega$				

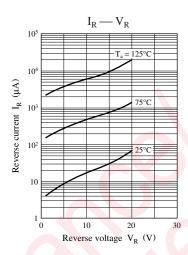
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

- 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. Absolute frequency of input and output is 250 MHz.
- 4. *: t_{rr} measurement circuit



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